Micro Electronics
Proto & Production

- Sub 2-Mil Lines
- .25 MM Pitch
- Stacked Blind & Buried Vias
- Ultra Thin Multi Layer Boards
  (12 Layers, 28-Mil Thickness)

Complete Design Assistance

www.micropcb.com
**Micro Electronics Via Structures**

**Micro Electronics Via Structures**

**Micro Electronics Capabilities**

**Microvia from Outer Layer to 1st Inner Layer**
- A1: Blind/Buried via laser drill diameter .002"
- A2: Laser drill capture pad diameter A1 + .004"
- A3: Laser drill target pad diameter A1 + .004"
- A4: Distance center to center staggered vias .005"
- A5:A1: Laser via plating aspect ratio >1:1

**Filled (Copper) Mechanical Drill Buried Via**
- D1: Buried via mechanical drill diameter .004"
- D2: Mechanical drill capture pad diameter D1 + .008"
- D3: Mechanical drill target pad diameter D1 + .008"
- D4: Dielectric thickness .005"
- D5: Innerlayer antipad clearance diameter D1 + .012"
- D4:D1: Mechanical via plating aspect ratio >16:1

**LPI Soldermask**
- Minimum thickness .0005"
- Registration tolerance +/-.001"
- Minimum SMD pad spacing for mask between pads .005"
- Minimum web width .002"

**Legend Specifications**
- Minimum text line width .0025"
- Registration tolerance +/-.003"
- Minimum character height .015"

**Complete Design Assistance**
- Design Assistance to Optimize Costs
- Impedance Stack-up Assistance
- Design for Manufacturability (DFM) Assistance

For Complete Design Guideline Details, Visit: www.micropcb.com

**Military • Medical • Automotive**

Please call us at: 1.800.763.7503
www.micropcb.com

Sierra Micro Electronics
1108 West Evelyn Avenue
Sunnyvale, CA 94086

www.protoexpress.com/micro